

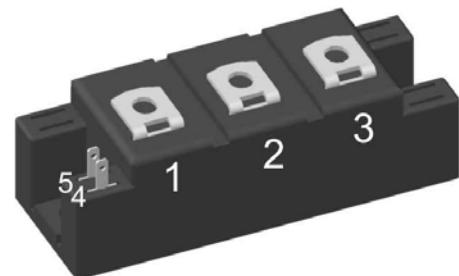
IGBT (NPT) Module

V_{CES} = 1200V
 I_{C25} = 135A
 $V_{CE(sat)}$ = 2.2V

Boost Chopper + free wheeling Diode

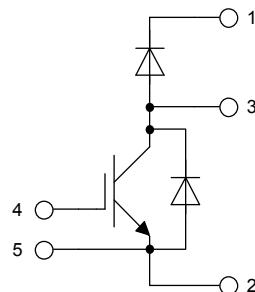
Part number

MID100-12A3



Backside: isolated

E72873



Features / Advantages:

- NPT IGBT technology
- low saturation voltage
- low switching losses
- switching frequency up to 30 kHz
- square RBSOA, no latch up
- high short circuit capability
- positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- ultra fast free wheeling diodes

Applications:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

Package: Y4

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Free Wheeling Diode FWD

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1200	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1200	V
I_R	reverse current, drain current	$V_R = 1200 V$ $V_R = 1200 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		1 3	mA
V_F	forward voltage drop	$I_F = 75 A$ $I_F = 150 A$ $I_F = 75 A$ $I_F = 150 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		2.50 2.90 1.80 2.10	V
I_{FAV}	average forward current	$T_C = 80^\circ C$ DC current $d = 1$	$T_{VJ} = 150^\circ C$		75	A
V_{F0} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ C$		1.30 7.5	V mΩ
R_{thJC}	thermal resistance junction to case				0.45	K/W
R_{thCH}	thermal resistance case to heatsink			0.45		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		280	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}; V_R = 0 V$	$T_{VJ} = 45^\circ C$		700	A
C_J	junction capacitance	$V_R = 600 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	30		pF

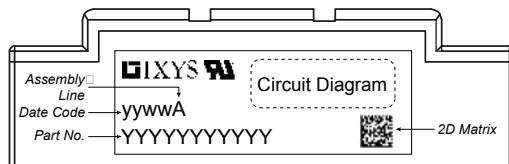
Boost IGBT

Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$			1200	V	
V_{GES}	max. DC gate voltage				± 20	V	
V_{GEM}	max. transient gate emitter voltage				± 30	V	
I_{C25}	collector current	$T_c = 25^\circ C$			135	A	
I_{C80}		$T_c = 80^\circ C$			90	A	
P_{tot}	total power dissipation	$T_c = 25^\circ C$			560	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_c = 75A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$	2.2	2.7	V	
			$T_{VJ} = 125^\circ C$	2.7		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_c = 3mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	4.5	5.5	6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$		5	mA	
			$T_{VJ} = 125^\circ C$	7.5		mA	
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			300	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_c = 75 A$		350		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600 V; I_c = 75 A$ $V_{GE} = \pm 15 V; R_G = 15 \Omega$		100		ns	
t_r	current rise time			50		ns	
$t_{d(off)}$	turn-off delay time			650		ns	
t_f	current fall time			50		ns	
E_{on}	turn-on energy per pulse			12.1		mJ	
E_{off}	turn-off energy per pulse			10.5		mJ	
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 15 \Omega$	$T_{VJ} = 125^\circ C$				
I_{CM}		$V_{CEmax} = 1200 V$			150	A	
SCSOA	short circuit safe operating area	$V_{CEmax} = 1200 V$	$V_{CE} = 1200 V; V_{GE} = \pm 15 V$ $R_G = 15 \Omega$; non-repetitive				
t_{sc}	short circuit duration	$T_{VJ} = 125^\circ C$		10	μs		
I_{sc}	short circuit current		270		A		
R_{thJC}	thermal resistance junction to case				0.22	K/W	
R_{thCH}	thermal resistance case to heatsink				0.22	K/W	

Boost Diode BD

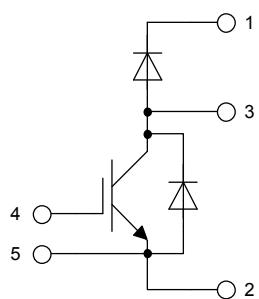
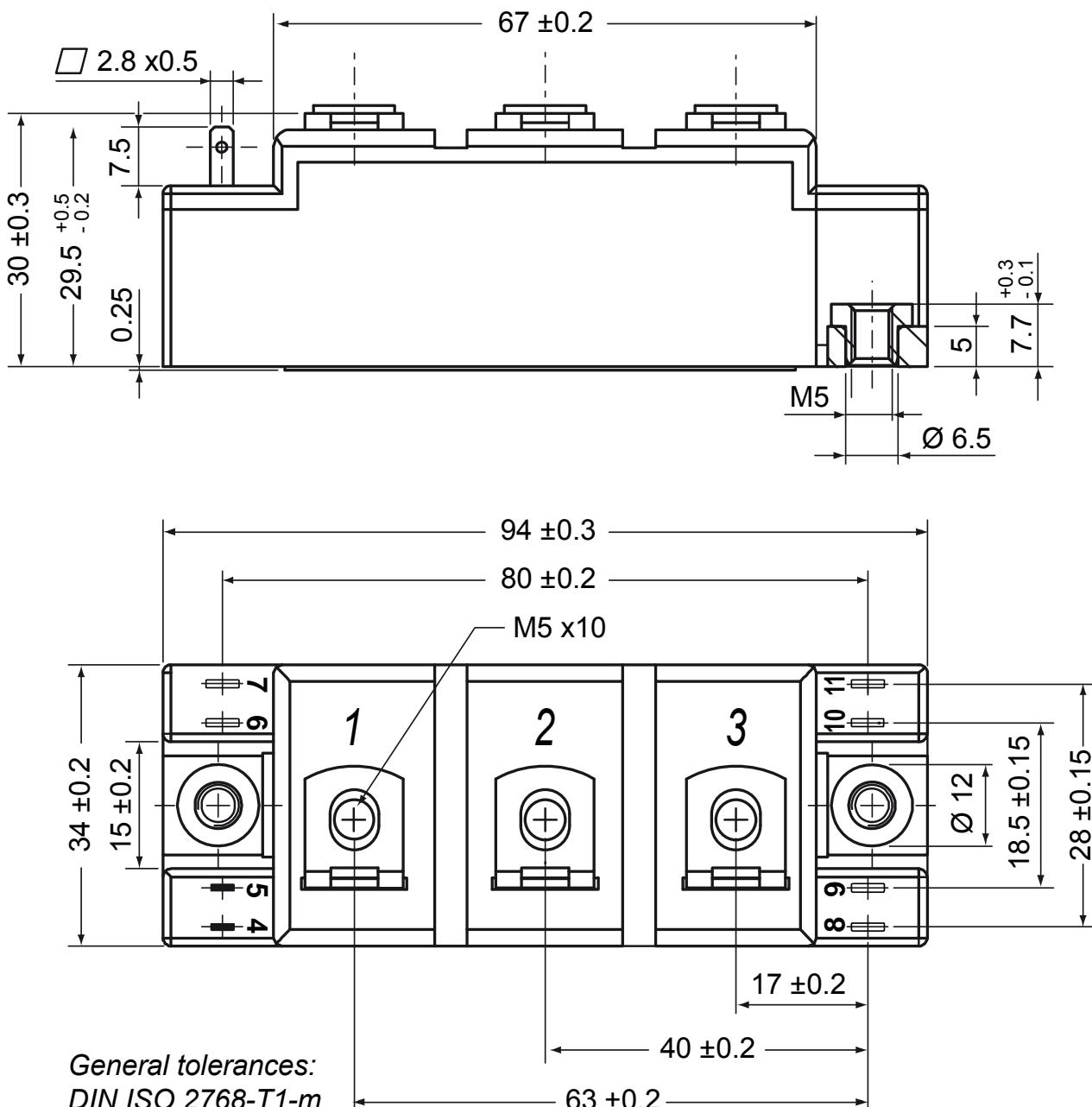
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200	V	
I_{F25}	forward current	$T_c = 25^\circ C$		150	A	
I_{F80}		$T_c = 80^\circ C$		95	A	
V_F	forward voltage	$I_F = 75A$	$T_{VJ} = 25^\circ C$		2.50	V
			$T_{VJ} = 125^\circ C$	1.70		V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$		1	mA
			$T_{VJ} = 125^\circ C$	1.5		mA
Q_{rr}	reverse recovery charge	$V_R = 600 V$ $-di_F/dt = 600 A/\mu s$ $I_F = 75A; V_{GE} = 0 V$		7		μC
				62		A
				200		ns
				1.2		mJ
R_{thJC}	thermal resistance junction to case				0.45	K/W
R_{thCH}	thermal resistance case to heatsink				0.45	K/W

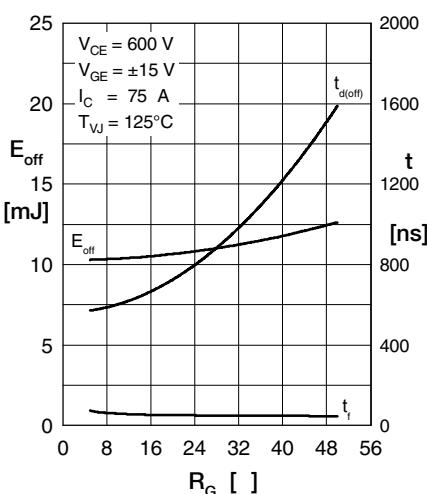
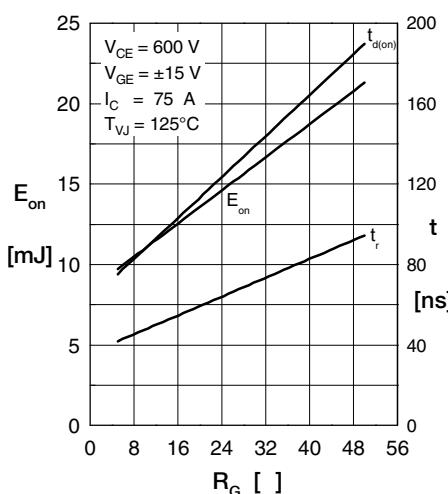
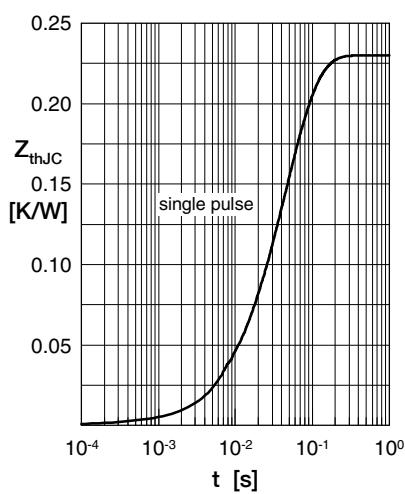
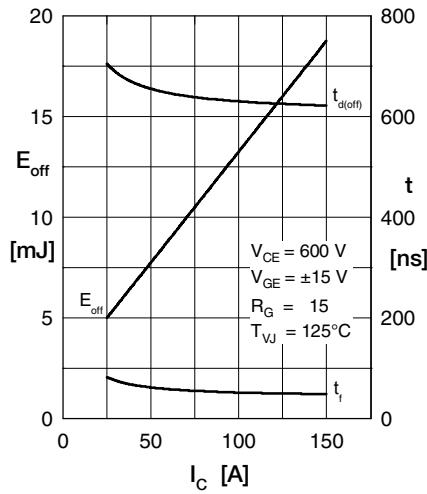
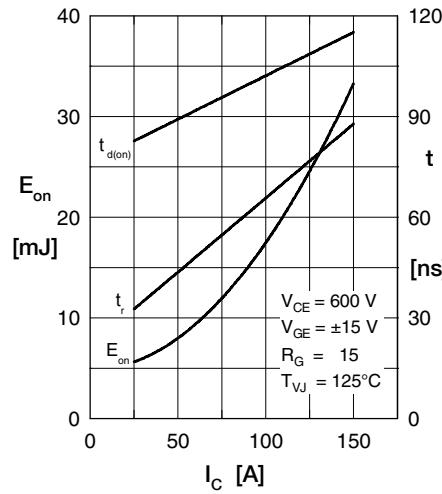
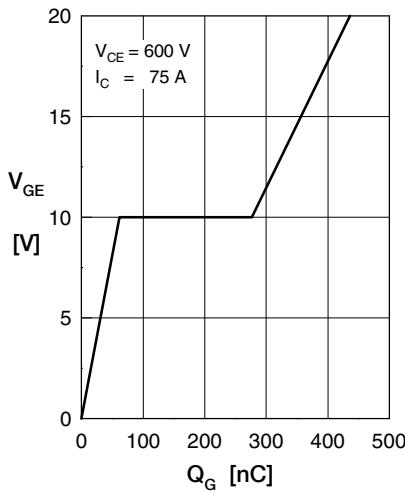
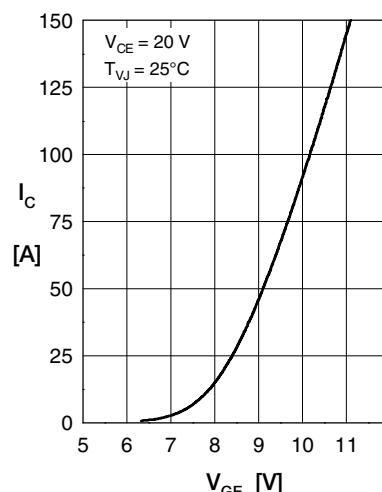
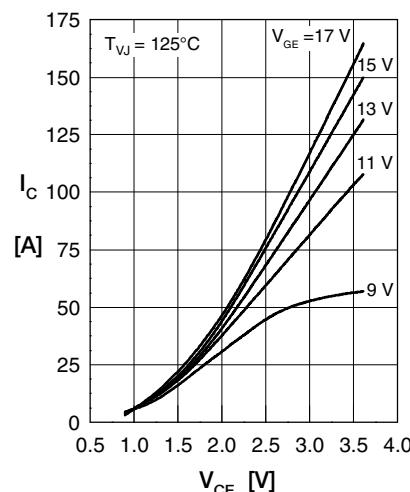
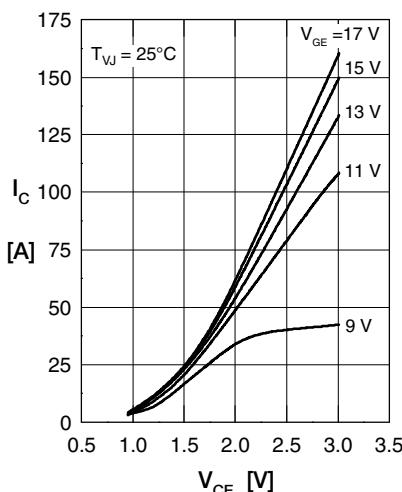
Package Y4			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			300	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight				108		g
M_D	mounting torque		2.25		2.75	Nm
M_T	terminal torque		4.5		5.5	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air		terminal to terminal	14.0	10.0	mm
$d_{Spb/Abp}$			terminal to backside	16.0	16.0	mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 3000	V V



Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MID100-12A3	MID100-12A3	Box	6	466816

Outlines Y4



Boost IGBT

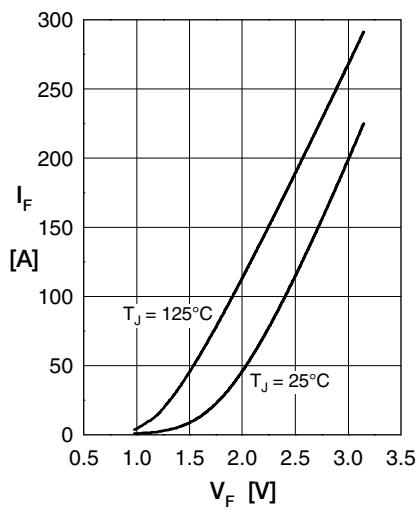
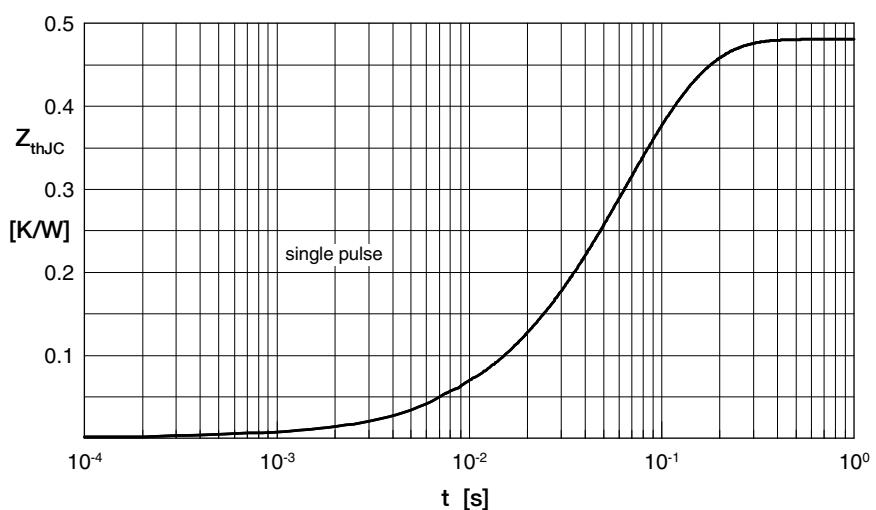
Boost Diode BDFig. 1 Typ. Forward current vs. V_F 

Fig. 2 Typ. transient thermal impedance junction to case